

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

icants: L.W. Graham et al.

Attorney Docket No.: SEMT116060

Application No.: 09/429,446

Group Art Unit:

1741

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Examiner:

W. Leader

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Title:

METHOD, CHEMISTRY, AND APPARATUS FOR NOBLE METAL ELECTROPLATING ON A MICROELECTRONIC WORKPIECE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Seattle, Washington
December 13, 2001

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

- 1. X Copies of the listed patents, publications, and other information are enclosed for the Examiner's use.
- Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed within three months of the filing date of the national application (other than a CPA), within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, before the mailing date of a first Office Action on the merits, or before the mailing date of a first Office Action after the filing of an RCE.
- 3. X The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the

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appropriate length required upon the filing of any reply during the entire prosecution of this application.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, Washington, D.C. 20231, on the below date.

Date:

December 13, 2001

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